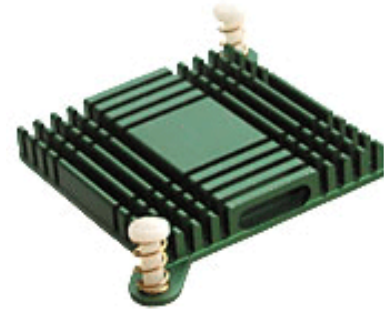




BOARD LEVEL COOLING – 3729

3729 is a square pin fin board level heat sink designed to cool BGA and FPGA devices. Representative image only.



ORDERING INFORMATION

Part Number	Device Type
372924M02000G	BGA, FPGA

HEAT SINK DETAILS

Property	Details
Material	Aluminum
Finish	Green Anodize
Device Attachment Options	Push Pin
Thermal Interface Material	-

Property	Details
Heat Sink Width (mm)	37.4
Heat Sink Length (mm)	37.4
Heat Sink Height (mm)	6.0
Heat Sink Mounting Direction	Horizontal, Vertical

MECHANICAL & PERFORMANCE

Drawing dimensions are shown in mm, (in)

